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E-000216/2026

Answer given by Executive Vice-President Virkkunen
on behalf of the European Commission
(24.3.2026)

The Commission shares the objective of strengthening Europe's technological sovereignty. Under the European Chips Act¹, the Commission and the European Semiconductor Board monitor the semiconductor value chain and may carry out targeted analytical assessments. These can also cover memory, mapping EU demand, capacity and supply-chain risks. While the EU currently has limited capabilities in standard random-access memory (RAM) and data-centre memory components, the Commission supports research and development via open, competitive calls (e.g. under the Chips Joint Undertaking) in embedded and specialty memories, including promising next-generation non-volatile memory developments, for automotive, industrial and edge/Internet of Things (IoT) applications.

It has also authorised State aid under Article 107(3) of the Treaty on the Functioning of the European Union (TFEU)² for semiconductor research and first industrial deployment in the context of two Important Projects of Common European Interest (IPCEI) on microelectronics in 2018 and 2023, totalling up to EUR 10 billion.

Under the European Chips Act, the Commission aims to increase manufacturing capacity of semiconductor products, including RAM. The type of manufacturing facility to support depends primarily on companies' and Member States' decisions. Member States may grant support if it complies with EU State-aid rules and may notify support for projects for first-of-a-kind facilities under Article 107(3) TFEU to undergo Commission approval; to date, up to EUR 13.8 billion has been approved.

¹ <https://digital-strategy.ec.europa.eu/en/policies/european-chips-act>.

² <https://eur-lex.europa.eu/legal-content/EN/TXT/HTML/?uri=CELEX:12008E107>.